

SID

Factory: Rot am See

Article:

ML4

Provided:

Customer:

Date:

31.03.2026

WÜRTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-035my 330x490mm	50200242	35	VS	1		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	306		2		
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	0		3		
		35	L2			
B-STD-FR4-ML-0.711mm-035+035-TG150-HF...	50203135	710		4	A00	B00
		35	L3			
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	306		5		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		6		
A-RS Kupferfolie-035my 330x490mm	50200242	35	RS	7		

Thickness after Pressing

B00: 1440 µm Tol+: 155 µm Tol-: 155 µm Dmax: 1595 µm Dmin: 1285 µm

Thickness over all

0 µm Tol+: 0 µm Tol-: 0 µm Dmax: 0 µm Dmin: 0 µm

Demand for customer

Thickness (D): 1550 µm Tol+: 155 µm Tol-: 155 µm Dmax: 1705 µm Dmin: 1395 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal: 1462 µm

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